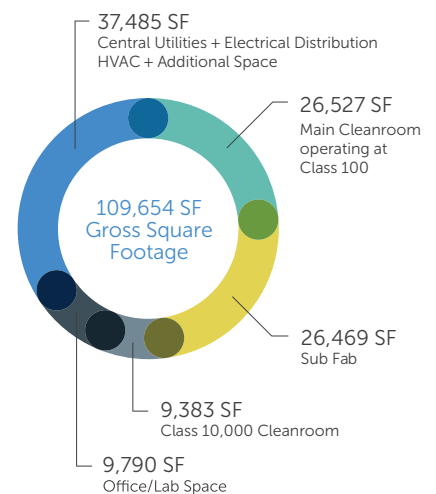


# What is BRIDG?

- BRIDG is a not-for-profit, public-private partnership for advanced sensors and next-generation nanoscale electronic systems.
- BRIDG provides research, development, and manufacturing capabilities focused on advanced system integration solutions, smart sensor platforms, and non-CMOS electronics devices.
- Designed as one of the most versatile 200mm microelectronics fabs, BRIDG has space to accommodate a variety of partner-funded activities. The two-story building is 54' tall with two cleanrooms; one operating at Class 100 standards and the other at Class 10,000.
- BRIDG provides a trusted and assured fabrication facility for the development and low-volume production of microelectronic devices.
- Centrally located in Florida less than 20 minutes from the Orlando International Airport and within a mile of Florida's Turnpike at NeoCity— a 500-acre master-planned intuitive community of innovation.

BRIDG unites ideas with industry to accelerate the manufacturing development of emerging technologies and spark tomorrow's innovation.

With support from Osceola County, the University of Central Florida, the Florida High Tech Corridor Council, and others, BRIDG facilitates the connection between innovation and industry and is "Bridging the Innovation Development Gap" that makes commercialization possible.

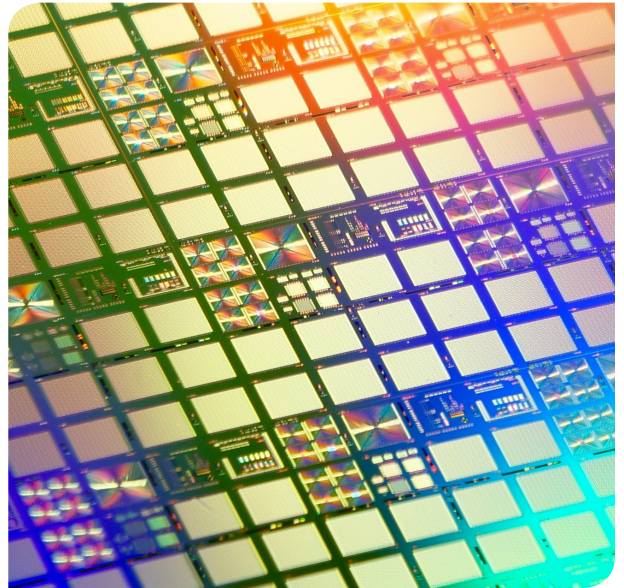


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Bridging the Innovation Development Gap

## Solutions

- Accelerate high potential technologies into next-generation products and systems
- Develop and provide low-volume manufacturing
- Provide capability for proof of concept, custom development, and pilot production
- Flexible IP management and protection
- Provide research and academic institutions with a path to commercialize their IP
- Provide trusted and assured semiconductor manufacturing



## BRIDG Technologies

- 2.5 / 3D Device Integration, Test, and Packaging
- Hardware and System Secure Devices and Processes such as CMOS-Integratable PUF technology
- Advanced Materials and Device Development Lines – III/V and other novel materials integrated into silicon-based devices
- Sensors, Imagers, RF, Power, and other heterogeneous integrated devices.
- Materials Focus – GaAs, InGaAs, InP, GaSb
- Photonics, High Speed Electronic Systems, and Design Center (via imec)
- 200mm BEOL processing using copper dual damascene



## Wafer Processing Milestones

October 2017 ..... May 2018 ..... August 2018 ..... October 2018

Tools installation initiated

First patterned wafer successfully created

Critical testing of wafers

First lot of wafers successfully completed for setting up processes